

AON2240

40V N-Channel MOSFET

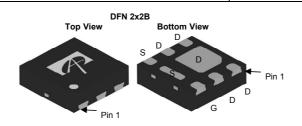
General Description

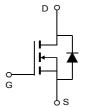
The AON2240 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{\text{DS(ON)}}$. This device is ideal for load switch and battery protection applications.

Product Summary

 $\begin{array}{lll} V_{DS} & 40V \\ I_{D} \; (at \, V_{GS} \! = \! 10V) & 8A \\ R_{DS(ON)} (at \, V_{GS} = \! 10V) & < 21 m\Omega \\ R_{DS(ON)} (at \, V_{GS} = \! 4.5V) & < 29 m\Omega \end{array}$







Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	40	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain T _A =25°C			8	
Current G	T _A =100°C	'D	6	A
Pulsed Drain Current C		I _{DM}	32	
	T _A =25°C	P _D	2.8	W
Power Dissipation A	T _A =70°C	T D	1.8	VV
Junction and Storage	Temperature Range	T _J , T _{STG}	-55 to 150	°C

Thermal Characteristics							
Parameter		Symbol	Symbol Typ Max		Units		
Maximum Junction-to-Ambient A	t ≤ 10s	D	37	45	°C/W		
Maximum Junction-to-Ambient AD	Steady-State	$\kappa_{\theta JA}$	66	80	°C/W		



Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC F	PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V		40			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V T _J =55°C				1	μΑ
						5	
I_{GSS}	Gate-Body leakage current	V_{DS} =0V, V_{GS} =±20V				±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$		1.4	1.9	2.4	V
I _{D(ON)}	On state drain current	V_{GS} =10V, V_{DS} =5V		32			Α
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =8A			16.8	21	mΩ
		Т	_J =125°C		24.5	31	11152
		V_{GS} =4.5V, I_D =4A			22.6	29	mΩ
g _{FS}	Forward Transconductance	V_{DS} =5V, I_D =8A			33		S
V_{SD}	Diode Forward Voltage	I _S =1A,V _{GS} =0V			0.75	1	V
Is	Maximum Body-Diode Continuous Curr	rent				3.5	Α
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, f=1MHz			415		pF
Coss	Output Capacitance				112		pF
C _{rss}	Reverse Transfer Capacitance				11		pF
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		1	2.2	3.5	Ω
SWITCHI	NG PARAMETERS						
Q _g (10V)	Total Gate Charge				6.5	12	nC
Q _g (4.5V)	Total Gate Charge	V _{GS} =10V, V _{DS} =20V, I _D =8A			3	6	nC
Q_{gs}	Gate Source Charge				1.2		nC
Q_{gd}	Gate Drain Charge				1.1		nC
t _{D(on)}	Turn-On DelayTime	V_{GS} =10V, V_{DS} =20V, R_L =2.5 Ω , R_{GEN} =3 Ω			4		ns
t _r	Turn-On Rise Time				3		ns
t _{D(off)}	Turn-Off DelayTime				15		ns
t _f	Turn-Off Fall Time				2		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =8A, dI/dt=100A/μs			12.5		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =8A, dI/dt=100A/μs			3.5		nC

A. The value of R_{BJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_{A} =25° C. The Power dissipation P_{DSM} is based on R_{BJA} t \leq 10s value and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.

- D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.
- G. The maximum current rating is package limited.
- H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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B. The power dissipation P_D is based on $T_{J(MAX)}$ =150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J =25° C.

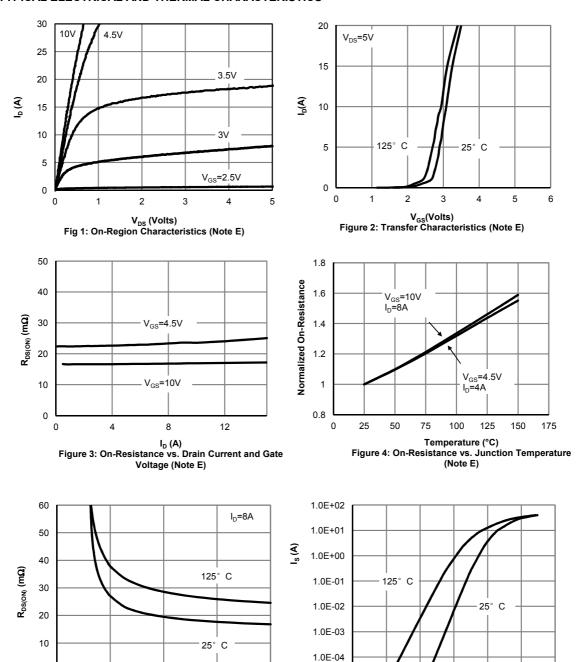


0 2

6

V_{GS} (Volts)
Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



10

1.0E-05

0.0

 $V_{\rm SD} = 0.0$ 0.2 0.4 0.6 0.8 1.0 1 $V_{\rm SD} = 0.00$ (Volts) Figure 6: Body-Diode Characteristics (Note E)



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

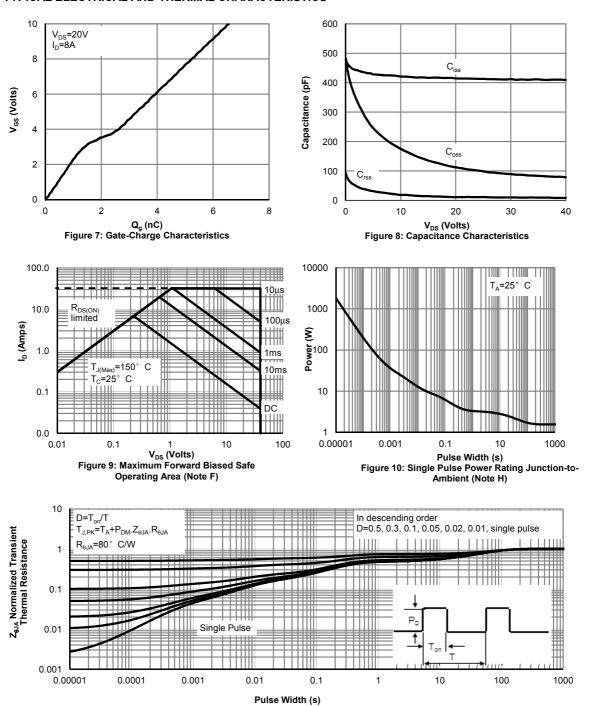
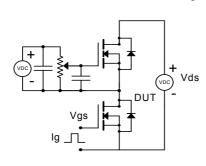
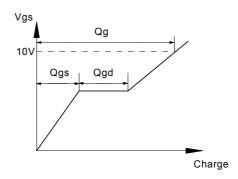


Figure 11: Normalized Maximum Transient Thermal Impedance (Note H)

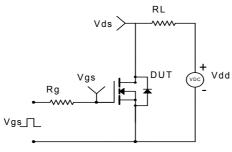


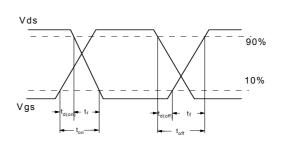
Gate Charge Test Circuit & Waveform



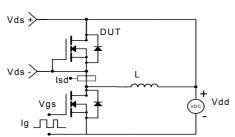


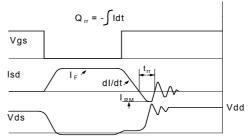
Resistive Switching Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms





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